### **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

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> Title of Invention

### ANOLYTE FOR COPPER PLATING

**Application Number:** 

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9799 Confirmation Number:

First Named Applicant:

MICHAEL YANG

Attorney Docket Number: AMAT7669P2

Art Unit:

1753

Search string:

( 5224504 or 5489341 or 5573023 or 5620581

or 5731678 or 5744019 or 5837120 or 5883762 or 5996241 or 6014817 or 6099702 or 6099712 or 6126798 or 6132857 or 6136163 or 6156167 or 6179983 or 6228231 or 6228232 or 6248222 or 6254742 or 6261433 or 6267853 or 6273110 or 6280582 or 6322674 or 6322678 or 6368475 or 6374837 or 6383352 or 6391166 or 6395101 or 6395152 or 6409892 or 6432821 or 6436249

or 6440295 or 6527920 or 6551487 or 6569299 or 6589401 or 5252196 or 6197181 or 6290833

or 6319387 or 6334937 or 6551479 or

20020074233 ).pn.

#### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
LV	1	5224504	1993-07-06	THOMPSON, ET AL.			
	· 2	5489341	1996-02-06	BERGMAN, ET AL.			
	3	5573023	1996-11-12	THOMPSON, ET AL.			
	4	5620581	1997-04-15	ANG			
	5	5731678	1998-03-24	ZILA, ET AL.			•
	6	5744019	1998-04-28	ANG			
	7	5837120	1998-11-17	FORAND, ET AL.			
	8	5883762	1999-03-16	CALHOUN, ET AL.			
	9	5996241	1999-12-07	THOMPSON, ET AL.	]		
W	10	6014817	2000-01-18	THOMPSON, ET AL.	]		

		·		
LV	11	6099702	2000-08-08	REID, ET AL.
	12	6099712	2000-08-08	RITZDORF, ET AL.
	13	6126798	2000-10-03	REID, ET AL.
	·14	6132857	2000-10-17	CHAMPENOIS, ET AL.
M	15	6136163	2000-10-24	CHEUNG, ET AL.
Hi	16	6156167	2000-12-05	PATTON, ET AL.
	17	6179983	2001-01-30	REID, ET AL.
	18	6228231	2001-05-08	UZOH
	19	6228232	2001-05-08	WOODRUFF, ET AL.
	20	6248222	2001-06-19	WANG
	21	6254742	2001-07-03	HANSON, ET AL.
M	22	6261433	2001-07-17	LANDAU
	23	6267853	2001-07-31	DORDI, ET AL.
	24	6273110	2001-08-14	DAVIS, ET AL.
Mi	25	6280582	2001-08-28	WOODRUFF, ET AL.
Mi	26	6322674	2001-11-27	BERNER, ET AL.
	27	6322678	2001-11-27	WOODRUFF, ET AL.
M	28	6368475	2002-04-09	HANSON, ET AL.
	29	6374837	2002-04-23	SCRANTON, ET AL.
$\prod$	30	6383352	2002-05-07	SHYU, ET AL.
	31	6391166	2002-05-21	WANG
	32	6395101	2002-05-28	SCRANTON, ET AL.
	33	6395152	2002-05-28	WANG
	34	6409892	2002-06-25	WOODRUFF, ET AL.
	35	6432821	2002-08-13	DUBIN, ET AL.
	36	6436249	2002-08-20	PATTON, ET AL.
	37	6440295	2002-08-27	WANG
LV	38	6527920	2003-03-04	MAYER, ET AL.
	39	6551487	2003-04-22	REID, ET AL.
	40	6569299	2003-05-27	REID, ET AL.
	41	6589401	2003-07-08	PATTON, ET AL.
	42	5252196	1993-10-12	SONNENBERG, ET AL.
	43	6197181	2001-03-06	CHEN
	44	6290833	2001-09-18	CHEN
	45	6319387	2001-11-20	KRISHNAMOORTHY, ET AL.
	46	6334937	2001-01-01	BATZ, JR, ET AL.
LV				

| LV | 47 | 6551479 | 2003-04-22 | GRAHAM, ET AL.

# **US Published Applications**

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
W	1	20020074233	2002-06-20	RITZDORF, ET AL.			

# Signature

Examiner Name	Date
Jan Von	7/13/05